

**Upcoming: November 26–30 MRS Fall Meeting, MRS.**

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313; bulletin@mrs.org.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the July 2001 MRS BULLETIN for September 2001 Calendar entries.

**OCTOBER 2001**

**1–3** Conf. on Fine Powder Processing, *State College, PA*. C. Knobloch, Particle Materials Ctr., The Pennsylvania State Univ., 225 Materials Research Lab., University Park, PA 16802-4801; 814-863-6156; fax 814-863-9704; e-mail clk18@psu.edu; conferenceinfo@cde.psu.edu.

**1–3** Intl. Conf. on Process Modeling and Powder Metallurgy & Particulate Materials, *Irvine, CA*. Metal Power Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail info@mpif.org; www.mpif.org.

**1–3** Symposium on Optical Materials for High Power Lasers, *Boulder, CO*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**1–4** Materialica Conf., *Munich, Germany*. Messe München GmbH, Zentralbereich Presse- und Öffentlichkeitsarbeit, Pressereferat MATERIALICA, Messegelände, D-81823 München, Germany; 49-89-9-49-20650; fax 49-89-9-49-20659; e-mail info@materialica.de; www.materialica.de.

**1–6** ▼ 9th Intl. Topical Meeting on Optics of Liquid Crystals, *Napoli, Italy*. G. Abbate, Dipt. de Scienze Fisiche, Univ. di Napoli "Federico II," Via Cintia, Monte S. Angelo, 80126 Napoli, Italy; 39-81-676118; fax 39-81-676346; e-mail olc2001@na.infn.it; www.na.infn.it/olc2001/.

**3–5** 2001 U.S. Workshop on the Physics and Chemistry of II–VI Materials, *Orlando, FL*. J. Lee, Palisades Convention Mgmt.; 212-460-8090; fax 212-460-5460; www.ii-viworkshop.org.

**3–5** Conf. on Photomask Technology and Management, *Monterey, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**5–7** ▼ MMRC—Optoelectronics Packaging Conf., *Washington, DC*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**5–12** 28th Annual Conf. on Federation of Analytical Chemistry and Spectroscopy Societies, *Detroit, MI*. C. Lilly, FACSS Natl. Office, 1201 Don Diego Ave., Santa Fe, NM 87505; 505-820-1648; fax 505-989-1073; e-mail jsjoberg@trail.com; http://facss.org/info.html.

**6–11** Euroconf. on Quantum Optics, *San Feliu de Guixols, Spain*. European Science Foundation, 1 quai Lezay-Marnésia, F-67080 Strasbourg Cedex, France; 33-388-76-71-35; fax 33-388-36-69-87; e-mail euresco@esf.org; www.esf.org/euresco.

**7–10** Conf. on Advances in Polyolefins III, *Sonoma, CA*. J.E. McGrath, Dept. of Chemistry, Virginia Tech, Blacksburg, VA 24061; 540-231-5976; fax 540-231-8517; e-mail jmcgrath@vt.edu; www.chem.umd.edu/~poly/poly.spon.html.

**7–12** 16th Conf. on Enzyme Engineering, *Potsdam, Germany*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**7–12** Conf. on Structural Ceramics and Ceramic Composites for High-Temperature Applications, *Seville, Spain*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

**8–10** Intl. Workshop on Photonics and Imaging in Biology and Medicine, *Wuhan, China*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**9–11** 34th Intl. Symposium on Microelectronics, *Baltimore, MD*. Intl. Microelectronics and Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**9–11** Advanced Metallization Conference (AMC), *Montreal, Canada*. Continuing Education in Engineering, UC Berkeley Extension, 1995 University Avenue, Berkeley, CA 94720-7010, USA; 510-642-4151; fax 510-642-6027; e-mail course@unx.berkeley.edu; www.unex.berkeley.edu/eng/metal.

**9–12** 54th Annual Gaseous Electronics Conf., *State College, PA*. R. McGrath, Conf. Secretary, Penn State Univ., 304 Old Main, University Park, PA 16802; 814-863-9580; fax 814-863-9659; e-mail mcgrath@psu.edu.

**10–13** ACS Midwest Regional Meeting, *Lincoln, NE*. American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

**11–14** Advanced Technology Workshop on Optoelectronics Packaging, *Bethlehem, PA*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**12–17** China Hi-Tech Fair on Advanced Materials, *Shenzhen, China*. China Hi-Tech Transfer Ctr., Shenzhen, China; 86-755-3065436; fax 86-755-3065471; e-mail cathyh@chtf.com; www.chtf.com.

**13** 2nd Dartmouth Molecular Materials Symposium, *Hanover, NH*. Dartmouth Molecular Materials Group, Dartmouth College, 6128 Burke Lab., Hanover, NH 03755-3564; 603-646-2710; fax 603-646-3946; e-mail dmmg@dartmouth.edu; www.dartmouth.edu/~dmmg/Oct.Symposium.html.

**14-17** ▼ 4th Annual Conf. on Fine, Ultrafine, and Nano Particles, *Chicago, IL*. S. Faust, Conf. Coordinator, Business Communications Co., Inc., 25 Van Zant St., Ste. 13, Norwalk, CT 06855; 203-853-4266; fax 203-853-0348; e-mail conference@bccresearch.com.

**14-17** ▼ 16th Natl. Educators' Workshop: Experiments in Engineering, Materials Science, and Technology, *Gaithersburg, MD*. J. Jacobs, School of Science and Technology, Norfolk State Univ., 700 Corpview Ave., Norfolk, VA 23504-8060; 757-823-8109; fax 757-823-8215; e-mail dplacaire@nsu.edu; http://MST-Online.nsu.edu/new.

**14-18** 6th Intl. Symposium on Self-Propagating High-Temperature Synthesis, *Haifa, Israel*. Dept. of Materials Engineering, TECHNION-Israel Inst. of Technology, Technion City, Haifa 32000, Israel; 972-4-829-2112; fax 972-4-832-1978; e-mail gutmanas@tx.technion.ac.il; www.technion.ac.il/technion/materials.

**14-18** 17th Interdisciplinary Laser Science Conf., *Long Beach, CA*. OSA Conf. Services, 2010 Massachusetts Ave. N.W., Washington, DC 20036-1023; 202-223-0920; fax 202-416-6100; e-mail confserv@osa.org; www.osa.org/annual.

**14-19** Conf. on Advanced Membrane Technology, *Barga, Italy*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**15** ▼ 13th Rio Grande Regional Symposium on Advanced Materials, *Albuquerque, NM*. J.C. Barbour, Sandia Natl. Labs., Albuquerque, NM 87185-1415; 505-844-5517; fax 505-844-1197; e-mail jbarbo@sandia.gov; www.nm-materials.org. **MRS.**

**15-18** 20th Intl. Congress on Applications of Lasers and Electro-Optics, *Jacksonville, FL*. B. Cohen, Laser Inst. of America, 13501 Ingenuity Dr., Ste. 128, Orlando, FL 32826; 407-380-1553; fax 407-380-5588; e-mail lia@laserinstitute.org; www.icaleo.org.

**15-18** ▼ IEEE Intl. Integrated Reliability Workshop, *S. Lake Tahoe, CA*. J. Suehle, Communications Vice Chair; 301-975-2247; fax 301-975-5668; e-mail john.suehle@nist.gov; www.irps.org/irw/.

**15-19** ▼ 2nd Intl. Conf. on Photonics for Transportation, *Sochy, Russia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**16-17** Conf. on Power Transmission Components—Advances in High-Performance Powder Metallurgy Applications, *Ypsilanti, MI*. Metal Power Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail info@mpif.org; www.mpic.org.

**16-19** Intl. Symposium on Optical Memory, *Taipei, Taiwan*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**17-19** 2nd Annual LED Conf., *San Diego, CA*. J. Olmstead, Conf. Director, Intertech Corp., 19 Northbrook Dr., Portland, ME 04105; 207-781-9615; fax 207-781-2150; e-mail jonathan@intertechusa.com; www.intertechusa.com.

**17-20** ACS Southwest Regional Meeting, *San Antonio, TX*. American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

**17-20** Fall Meeting of the APS Division of Nuclear Physics, *Maui, HI*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; www.aps.org.

**18-19** ▼ Biomaterials Conf.—The Next Frontiers: Biomedical, Bioelectronic, Biomaterialization, Bioanalytical, *Newark, DE*. Engineering Outreach, Univ. of Delaware, Newark, DE 19716-3101; 302-831-4863; fax 302-831-8179; e-mail enggoutreach@udel.edu; www.udel.edu/engg/outreach/Biomaterials.htm.

**21-25** Intl. Workshop on Flow and Fracture of Advanced Glasses, *Rennes, France*. V. Keryvin, Univ. Rennes1, Larmaur, 35042 Rennes, France; 33-2-9928-2685; fax 33-2-9928-1600; e-mail vincent.keryvin@univ-rennes1.fr; www.larmaur.univ-rennes1.fr/fafg.

**22-23** 4th North American Orbital Welding Symposium, *Rosemont, IL*. Astro Arc Polysoude, W133 N5138 Campbell Dr., Menomonee Falls, WI 53051; 414-783-2720; fax 414-783-2730; e-mail mbaer@polysoude.com; www.polysoude.com.

**22-24** 4th Biennial Conf. on Emulsion Polymers/Polymer Colloids, *Orlando, FL*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 845-255-0757; fax 845-255-0978; e-mail info@ims-np.org; http://ims-hp.org.

**22-24** Powder Metallurgy Congress, *Nice, France*. European Powder Metallurgy Assoc., Old Bank Bldgs., Bellstone, Shrewsbury SY1 1HU, UK; 44-1743-248-899; fax 44-1743-362-968; e-mail info@epma.com; www.epma.com.

**22-26** OSA Annual Meeting and 16th Interdisciplinary Laser Science Conf., *Providence, RI*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-223-8130; fax 202-223-1096; e-mail confserv@osa.org; www.osa.org/mtg\_conf/annual.

**25-26** 8th Sampling, On-Site Analysis, and Sample Preparation Conf., *Pittsburgh, PA*. B. Sherman, PACS, Inc., 409 Meade Dr., Coraopolis, PA 15108-9616; 800-367-2587; fax 724-457-1214; e-mail hnpacs@aol.com; http://members.aol.com/hnpacs/pacs.htm.

**28-31** 43rd Mechanical Working and Steel Processing Conf., *Charlotte, NC*. Iron & Steel Society, 186 Thorn Hill Rd., Warrendale, PA 15086-7528; 724-776-1535; fax 724-776-0430; e-mail custserv@iss.org; www.iss.org.

**28-31** ACS Western Regional Meeting, *Santa Barbara, CA*. American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

**28-2** Intl. Conf. on Silicon Carbide and Related Materials, *Tsukuba, Japan*. H. Okumura, Electrotechnical Lab., 1-1-4 Umezono, Tsukuba, Ibaraki 305-8565, Japan; www.icscrm2001.gr.jp/.

**29-31** ▼ Metal Forming and Fabricating Conf., *São Paulo, Brazil*. M. Carpenter, 55-11-3824-5300; e-mail mc@arandanet.com.br; www.arandanet.com.br/~mmed/ccm2001/index.html.

**29-2** 48th Natl. American Vacuum Society Symposium, *San Francisco, CA*. American Vacuum Society Natl. Office, 120 Walls St., 32nd Fl., New York, NY 10005; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; www.vacuum.org.

**29-2** Meeting of the APS Div. of Plasma Physics, *Long Beach, CA*. APS Headquarters, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

**30-31** 4th Conf. on Materials for Lean Weight Vehicles, *Gaydon, UK*. L. Bromley, IOM Communications, 1 Carlton House Terrace, London SW1Y 5DB, UK; 44-20-7451-7302; fax 44-20-7839-2289; e-mail Lisa\_Bromley@materials.org.uk.

## NOVEMBER 2001

**1-2** ▼ 2nd ABET Intl. Congress on Education, Accreditation, and Practice: The Knowledge Economy—Global Challenges for Engineering, Computing, and Technology, *Lake Tahoe, NV*. 2001 ABET Annual Meeting, 11 Market Place, Ste. 1050, Baltimore, MD 21202-4012; www.abet.org.

**4-8** 33rd Intl. SAMPE Technical Conf., *Seattle, WA*. Society for the Advancement of Material and Process Engineering, P.O. Box 2459, Covina, CA 91722-8459; 626-331-0616; fax 626-332-8929; e-mail sampereg@aol.com; www.sampe.org.

**4-8** Intl. Conf. on Advanced Ceramics and Glasses, *Maui, HI*. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.acers.org/meetings/.

**4-8** TMS Fall Meeting, *Indianapolis, IN*. TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail weissp@tms.org; www.tms.org.

**4-9** AIChE Annual Meeting, *Reno, NV*. Meetings Dept., American Inst. of Chemical Engineers, 3 Park Ave., New York, NY 10016-5991; 212-591-7338; fax 212-591-8894; e-mail meetmail@aiche.org; www.aiche.org/conferences/.

**4-10** ▼ IEEE Nuclear Science Symposium and Medical Imaging Conf., *San Diego, CA*. A. Lavietes, Lawrence Livermore Natl. Lab., 7000 East Ave., Livermore, CA 94550-9234; 925-423-6766; fax 925-423-5080; e-mail lavietes1@llnl.gov; www.nss-mic.org.

**5-7** 2nd Intl. Symposium on Adhesion Aspects of Thin Films, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/adhft2.htm.

**6-7** ▼ ASM Materials Solutions Conf., and 34th Annual Convention of the Intl. Metallographic Society, *Indianapolis, IN*. ASM Intl., 9639 Kinsman Rd., Materials Park, OH 44073-0002; 440-338-5151; fax 440-338-4634; www.asminternational.org/indy2001.

**7-9** 3rd Intl. Symposium on Adhesion Measurement of Thin Films and Coatings, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/adhmeas3.htm.

**7-10** Intl. Symposium on Optoelectronics and Microelectronics, *Nanjing, China*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**8-10** ▼ 3rd Advanced Technology Workshop on Packaging of MEMS and Related Micro Integrated Nanosystems, *Scotts Valley, CA*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; e-mail mems@engr.uark.edu; www.imaps.org.

**11-14** 59th Electric Furnace Conf., *Phoenix, AZ*. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersvc@acers.org; www.ceramics.org.

**11-16** ASME Intl. Mechanical Engineering Congress, *New York, NY*. American Society of Mechanical Engineers, 3 Park Ave., New York, NY 10016-5990; 1-800-843-2763; e-mail www.infocentral@asme.org; www.asme.org.

**11-16** Conf. on Integrating Materials Science into Engineering Structures and Devices, *Lake Arrowhead, CA*. United Engineering Foundation, 3 Park Ave., 27th Floor, New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org/engfnd/lar/html.

**12-16** 45th Annual Magnetism and Magnetic Materials Conf., *Seattle, WA*. 2001 MMM Conf., Courtesy Associates, 2000 L St. N.W., Ste. 710, Washington, DC 20036; 202-973-8668; fax 202-973-8722; e-mail magnetism@courtesyassoc.com; www.magnetism.org.

**14-16** 3rd Intl. Conf. on Organic Light Emissive Devices, *San Diego, CA*. J. Scheld, Intertech Conferences, 19 Northbrook Dr., Portland, ME 04105; 207-781-9800; fax 207-781-2150; e-mail info@intertechusa.com; www.intertechusa.com.

**14-17** Workshop on Organic/Inorganic Hybrid Materials, *Sonoma, CA*. [www.chem.umr.edu/~poly/poly.spon.html](http://www.chem.umr.edu/~poly/poly.spon.html).

**19-22** ▼ 3rd IMAPS Intl. Symposium on Electronic Materials and Packaging, *Cheju Island, Korea*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; [www.imaps.org](http://www.imaps.org).

**26-27** MMC VIII Metallic Composites and Foams, *London, UK*. L. Bromley, IOM Communications, 1 Carlton House Terrace, London SW1Y 5DB, UK; 44-20-7451-7302; fax 44-20-7839-2289; e-mail [Lisa\\_Bromley@materials.org.uk](mailto:Lisa_Bromley@materials.org.uk).

**26-30** Intl. Symposium on Photonics and Applications, *Singapore*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [info@spie.org](mailto:info@spie.org); [www.spie.org](http://www.spie.org).

**26-30** MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail [info@mrs.org](mailto:info@mrs.org); [www.mrs.org](http://www.mrs.org). MRS.

**27-30** Intl. Conf. on Accelerator and Large Experimental Physics, *San Jose, CA*. ICALEPCS 2001 Secretariat, Centennial Conferences, 4800 Baseline Rd., Ste. A-112, Boulder, CO 80303; 303-499-2299; fax 303-499-2599; e-mail [icalepcs@centennialconferences.com](mailto:icalepcs@centennialconferences.com); <http://icalepcs2001.slac.stanford.edu/>.

## DECEMBER 2001

**2-5** Niobium Conf., *Orlando, FL*. D.G. Howden, 3285 Wilson Rd., P.O. Box 544, Sunbury, OH 43074-0544; fax 740-965-2366; e-mail [niobium2001@worldnet.att.net](mailto:niobium2001@worldnet.att.net).

**3-5** 2nd Intl. Symposium on Polyimides and Other High Temperature Polymers, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail [rhl@mstconf.com](mailto:rhl@mstconf.com); <http://mstconf.com/polyim2.htm>.

**3-6** Australasian Conf. on Optics and Laser Spectroscopy, *Brisbane, Queensland, Australia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [spie@spie.org](mailto:spie@spie.org); [www.spie.org](http://www.spie.org).

**3-7** 10th Intl. Congress of Fracture, *Honolulu, HI*. A. Hill, ICF10 Congress Secretariat, Elsevier Science, The Boulevard, Langford Lane, Kidlington, Oxford OX5 1GB, UK; 44-1865-843-643; fax 44-1865-843-958; e-mail [a.richardson@elsevier.co.uk](mailto:a.richardson@elsevier.co.uk); [www.elsevier.com](http://www.elsevier.com).

**3-7** Pacific Polymer Federation Conf., *Oaxaca City, Mexico*. T. Ogawa, Inst. de Investigaciones en Materiales, UNAM, Ap. 70-360, CU, Coyoacan, Mexico DF 04510, Mexico; 52-5-622-4583; fax 52-5-616-1201; e-mail [ogawa@servidor.unam.mx](mailto:ogawa@servidor.unam.mx); [www.chem.umr.edu/~poly/poly.spon.html](http://www.chem.umr.edu/~poly/poly.spon.html).

**5-7** Intl. Semiconductor Device Research Symposium, *Georgetown, Washington DC*. A. Iliadis, ISDRS '01 Symposium Chair, Dept. of Electrical and Computer Engineering, Univ. of Maryland, College Park, MD 20742; e-mail [agis@eng.umd.edu](mailto:agis@eng.umd.edu); [www.ece.umd.edu/ISDRS\\_2001](http://www.ece.umd.edu/ISDRS_2001).

**5-8** 3rd Intl. Symposium on Environmental Hydraulics, *Tempe, AZ*. R. Rankin, ISEH 2001 Secretary, Arizona State Univ., Dept. of Mechanical and Aerospace Engineering, P.O. Box 876106, Tempe, AZ 85287-6106; 480-965-3207; fax 480-965-1384; e-mail [iseh@enpop2.eas.asu.edu](mailto:iseh@enpop2.eas.asu.edu); [www1.eas.asu.edu/~iseh2001/](http://www1.eas.asu.edu/~iseh2001/).

**6-7** 8th Intl. Symposium on Metallized Plastics, *Newark, NJ*. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail [rhl@mstconf.com](mailto:rhl@mstconf.com); <http://mstconf.com/metalplas8.htm>.

**11-15** 4th Pacific Rim Intl. Conf. on Advanced Materials and Processing, *Honolulu, HI*. S. Hanada, Tohoku Univ., Inst. for Materials Research, Katahira 2-1-1, Aoba-ku, Sendai 980-8577, Japan; 81-22-215-2115; fax 81-22-215-2116; e-mail [ccpricm4@imr.tohoku.ac.jp](mailto:ccpricm4@imr.tohoku.ac.jp).

**11-15** 11th Intl. Workshop on the Physics of Semiconductor Devices, *New Delhi, India*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [spie@spie.org](mailto:spie@spie.org); [www.spie.org](http://www.spie.org).

**17-19** Intl. Symposium on Microelectronics and MEMS, *Adelaide, Australia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [spie@spie.org](mailto:spie@spie.org); [www.spie.org](http://www.spie.org).

## JANUARY 2002

**6-11** 13th Intl. Conf. on Ternary and Multinary Compounds, *Dead Sea, Israel*. D. Cahen, Dept. of Materials and Interfaces, Weizmann Inst. of Science, Rehovoth, Israel 76100; 972-0-89-34-2246; fax 972-0-89-34-4139; e-mail [david.cahen@weizmann.ac.il](mailto:david.cahen@weizmann.ac.il); [www.weizmann.ac.il/material/](http://www.weizmann.ac.il/material/).

**6-12** Winter Conf. on Plasma Spectrochemistry, *Scottsdale, AZ*. R. Barnes, ICP Information Newsletter, Inc., P.O. Box 666, Hadley, MA 01003-0666; 413-256-8942; fax 413-256-3746; e-mail [winterconf@chem.umass.edu](mailto:winterconf@chem.umass.edu); [www.chem.umass.edu/WinterConf2002](http://www.chem.umass.edu/WinterConf2002).

**7-9** ▼ 1st North American Perpendicular Magnetic Recording Conference (NAPMRC2002), *Coral Gables, FL*. [info@napmrc.org](mailto:info@napmrc.org); [www.physics.miami.edu/napmrc](http://www.physics.miami.edu/napmrc). Endorsed.

**13-17** Conf. on Thermal Challenges in Next Generation Electronic Systems, *Santa Fe, NM*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail [engfnd@aol.com](mailto:engfnd@aol.com); [www.uefoundation.org](http://www.uefoundation.org).

**13-18** 26th Annual Intl. Conf. on Advanced Ceramics and Composites, *Cocoa Beach, FL*. Technical Program Coordinator, American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; fax 614-794-5882; e-mail [jdvais@acers.org](mailto:jdvais@acers.org).

**23-25** 2nd Intl. Colloquium on Modeling of Glass Forming and Tempering, *Valenciennes, France*. P. Moreau, Colloquium Organizer, M.G.F.T. 2002, L.A.M.I.H./L.G.M., Univ. de Valenciennes et du Hainaut-Cambrésis, 59313 Valenciennes Cedex 9, France; 33-3-27-51-13-84; fax 33-3-27-51-13-17; e-mail [philippe.moreau@univ-valenciennes.fr](mailto:philippe.moreau@univ-valenciennes.fr); [www.univ-valenciennes.fr](http://www.univ-valenciennes.fr).

## FEBRUARY 2002

**1-3** Intl. Conf. on Advances in Materials and Materials Processing, *Kharagpur, India*. Dept. of Metallurgical and Materials Engineering, Indian Inst. of Technology, Kharagpur 721 302, India; 91-3222-82280; fax 91-3222-55303; e-mail [icamp@metal.iitkgp.ernet.in](mailto:icamp@metal.iitkgp.ernet.in).

**3-6** ▼ OSA Meeting on Advanced Solid-State Lasers, *Québec City, Canada*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail [cust.serv@osa.org](mailto:cust.serv@osa.org); [www.osa.org/mtg\\_conf/](http://www.osa.org/mtg_conf/).

**7-10** ▼ OSA Meeting on Laser Applications to Chemical and Environmental Analysis, *Boulder, CO*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail [cust.serv@osa.org](mailto:cust.serv@osa.org); [www.osa.org/mtg\\_conf/](http://www.osa.org/mtg_conf/).

**17-21** TMS Annual Meeting, *Seattle, WA*. TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail [weissp@tms.org](mailto:weissp@tms.org); [www.tms.org/meetings/](http://www.tms.org/meetings/).

## MARCH 2002

**2-3** Conf. on Film Formation: Mechanism, Properties, and Characterization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail [info@ims-np.org](mailto:info@ims-np.org); <http://ims-np.org/>.

**2-3** Conf. on Polymer Degradation and Stabilization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail [info@ims-np.org](mailto:info@ims-np.org); <http://ims-np.org/>.

**4-6** 4th Biennial Conf. on Polymer Stabilizers and Modifiers, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail [info@ims-np.org](mailto:info@ims-np.org); <http://ims-np.org/>.

**4-6** Conf. on Film Formation: Science and Technology, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail [info@ims-np.org](mailto:info@ims-np.org); <http://ims-np.org/>.

**4-7** ▼ Manufacturing Applications Expo Intl.: AWS Welding Show and PMA METAL-FORM Expo, *Chicago, IL*. American Welding Society, 550 NW LeJeune Rd., Miami, FL 33126; 800-443-9353; fax 305-443-7559; e-mail [www.aws.org](http://www.aws.org); [www.maxinternational.com](http://www.maxinternational.com).

**7-8** ▼ Conf. on Advanced Microelectronic Manufacturing and Nanotechnologies, *Santa Clara, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [spie@spie.org](mailto:spie@spie.org); [www.spie.org](http://www.spie.org).

**11-13** ▼ IMAPS Intl. Conf. on Advanced Packaging and Systems, *Reno, NV*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; [www.imaps.org](http://www.imaps.org).

**11-13** Intl. Conf. on High-Performance Structures and Composites, *Seville, Spain*. Conf. Secretariat, HPSC 2002, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton, SO40 7AA, UK; 44-2380-293223; fax 44-2380-292853; e-mail [shanley@wessex.ac.uk](mailto:shanley@wessex.ac.uk); [www.wessex.ac.uk/conferences/2002/hpsc02](http://www.wessex.ac.uk/conferences/2002/hpsc02).

**12-14** ▼ Chemtex and Corrosion Conf., *Dubai, United Arab Emirates*. Intl. Expo-Consults L.L.C., P.O. Box 50006, Dubai, United Arab Emirates; 971-4-3435777; fax 971-4-3436115; e-mail [iec@emirates.net.ae](mailto:iec@emirates.net.ae); [www.expo-consults.com](http://www.expo-consults.com).

**17-20** 7th Intl. Multidisciplinary Conf. on Complexity and Fractals in the Sciences, *Granada, Spain*. M.M. Novak, School of Mathematics, Kingston Univ., Penrhyn Rd., Surrey KT1 2EE, UK; [www.kingston.ac.uk/fractal/](http://www.kingston.ac.uk/fractal/).

**17-21** ▼ Conf. on Smart Structures and Materials, *San Diego, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail [spie@spie.org](mailto:spie@spie.org); [www.spie.org](http://www.spie.org).

**18-22** APS March Meeting, *Indianapolis, IN*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail [meetings@aps.org](mailto:meetings@aps.org); [www.aps.org](http://www.aps.org).

**18-22** Intl. Solvent Extraction Conf., *Cape Town, South Africa*. Conf. Secretariat, Private Bag X3015, Randburg 2125, South Africa; 27-11-709-4255; fax 27-11-709-4326; e-mail [isec2002@mintek.co.za](mailto:isec2002@mintek.co.za); [www.isec2002.org.za](http://www.isec2002.org.za).

## APRIL 2002

**1-5** MRS Spring Meeting, *San Francisco, CA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail [info@mrs.org](mailto:info@mrs.org); [www.mrs.org](http://www.mrs.org). MRS.

**3-5** Intl. Conf. on High-Density Interconnect and Systems Packaging, *Santa Clara, CA*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; [www.imaps.org](http://www.imaps.org).

**8-10** Intl. Conf. on Metal Powder Deposition for Rapid Manufacturing, *San Antonio, TX*. S.E. Leatherman, Technical Programs Mgr., Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail [leatherm@mpif.org](mailto:leatherm@mpif.org); [www.mpi.org](http://www.mpi.org).

**9-11** Materials Congress 2002, London, UK. V. Morrison, IOM Communications, 1 Carlton House Terrace, London SW1Y 5DB, UK; 44-20-7451-7340; fax 44-20-7839-2289; www.materials.org.uk/congress2002/intro.htm.

**17-19** ▼ IMAPS Intl. Conf. on Electronics Packaging and 16th Microelectronics Show, Tokyo, Japan. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**28-1** 104th ACerS Annual Meeting, St. Louis, MO. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.ceramics.org.

**29-30** ▼ IMAPS Technology Workshop on Ceramic Applications for Microwave and Photonic Packaging, Providence, RI. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**29-2** Intl. Conf. on Characterization and Metrology for ULSI Technology, Gaithersburg, MD. L. Printz, NIST, Gaithersburg, MD 20899; e-mail lori.printz@nist.gov; www.eeel.nist.gov/812/conference/Endorsed.

## MAY 2002

**6-7** Intl. Conf. on Functionally Graded Materials, Denver, CO. S. Leatherman, Technical Programs Mgr., Metal Power Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

**12-17** 201st Meeting of the Electrochemical Society, Philadelphia, PA. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

**27-29** 7th European Symposium on Polymer Blends, Lyon-Villeurbanne, France. Secretariat, 7th European Symposium on Polymer Blends, Lab. des Matériaux Macromoléculaires, Bat J. Verne, INSA Lyon, 20 Ave. Albert Einstein, 69621, Villeurbanne Cedex, France; 33-4-72-43-8527; e-mail polymerblends@insa-lyon.fr; www.insa-lyon.fr/polymer\_blends/index.htm.

## JUNE 2002

**10-14** 8th Intl. Conf. on Electronic Materials, Xi'an, China. J. Cheng; 86-10-6894-4280; fax 86-10-6842-8640; e-mail cmrsec@public.bta.net.cn; www.c-mrs.org.cn/icem2002/C-MRS.

**16-18** European IMAPS Symposium, Cracow, Poland. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**16-20** Intl. Cryogenic Materials Conf., Xi'an, China. Y. Feng, Northwest Inst. for Non-ferrous Metal Research, P.O. Box 51, Xi'an, Shaanxi 710016, China; 86-29-623-1079; fax 86-29-623-1103; e-mail smrc@pub.xaonline.com.

**16-21** ▼ Powder Metallurgy and Particulate Materials World Congress, Orlando, FL. S. Leatherman, Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

**17-20** 1st Intl. Conf. on Multiscale Materials Modeling, London, UK. MMM Local Organising Committee, Dept. of Materials, Queen Mary, Univ. of London, London E1 4NS, UK; 44-20-7882-5159; fax 44-20-8981-9804; e-mail x.guo@qmw.ac.uk; www.multiscalemodelling.com.

**23-26** Intl. Conf. on Thermomechanical Processing, Sheffield, UK. Thermomechanical Processing: Mechanics, Microstructure, and Control, c/o IMMPTUS Admin. Office, Univ. of Sheffield, Sir Frederick Mappin Bldg., Mappin St., Sheffield S1 3JD, UK; 44-114-222-6018; fax 44-114-222-6015; e-mail tpmmc@sheffield.ac.uk; http://dyn052176.shef.ac.uk/conference\_2002.

**23-28** 11th Intl. Meeting on Lithium Batteries, Monterey, CA. IMLB 11 Conf. Secretariat, c/o The Electrochemical Society, Inc., 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/011/imlb11.html.

**26-28** Electronic Materials Conf., Santa Barbara, CA. TMS Meetings Services, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/meetings.

## JULY 2002

**1-5** Conf. on Coatings Science and Technology, Athens, Greece. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

**1-5** Intl. Conf. on Fuel Cells, Lucerne, Switzerland. European Fuel Cell Forum, P.O. Box 99, CH-5452 Oberrohrdorf, Switzerland; 41-56-496-7292; fax 41-56-496-4412; e-mail info@efcf.com; www.efcf.com.

**7-12** ▼ 7th Intl. Workshop on Positron and Positronium Chemistry, Knoxville, TN. S. Lantz, PPC7, Oak Ridge Natl. Lab., P.O. Box 2008, M.S. 6142, Oak Ridge, TN 37831; 865-574-4882; fax 865-574-8363; e-mail Sharon Lantz lantzsl@ornl.gov; www.ornl.gov/ppc.

**14-18** 13th Intl. Symposium on Transport Phenomena, Victoria, BC, Canada. S. Dost, ISTEP-13, Dept. of Mechanical Engineering, Univ. of Victoria, Victoria, BC, Canada V8W 3P6; 250-721-8898; fax 250-721-6294; e-mail istp13@uvic.ca; www.istp13.uvic.ca.

**14-19** CIMTEC Intl. Conf. on Materials and Technologies: 10th Intl. Ceramics Congress and 3rd Forum on New Materials, Florence, Italy. CIMTEC 2002 Secretariat, P.O. Box 174, 48018 Faenza, Italy; 39-546-22461; fax 39-546-664138; www.dinamica.it/cimte.

**14-19** Conf. on Polymer Colloids: Preparation and Properties of Aqueous Polymer Dispersions, Isee, Germany. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**17-19** ▼ Intl. Conf. on Smart Materials, Structures, and Systems, Bangalore, India. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**21-26** ▼ 4th World Congress on Particle Technology, Sydney, Australia. J. Hatte, Conf. Coordinator, ICMS Australasia Pty Ltd., Level 6, 2 Bridge St., Sydney NSW 2000, Australia; 61-2-9241-1478; fax 61-2-9251-3552; e-mail josie@icmsaust.com.au; www.wcpt4.com/.

**21-26** ▼ 8th Intl. Conf. on New Diamond Science and Technology, Melbourne, Australia. B. Hewitt, Conf. Mgmt., Old Physics Bldg., Univ. of Melbourne, Parkville 3010, Victoria, Australia; 61-3-8344-6389; fax 61-3-8344-6122; e-mail icndst-8@unimelb.edu.au; www.conferences.unimelb.edu.au/icndst-8.

**29-2** 26th Intl. Conf. on the Physics of Semiconductors, Edinburgh, Scotland. Conf. Dept., ICPS2002, Inst. of Physics, 76 Portland Place, London W1B 1NT, England; 44-20-7470-4800; fax 44-20-7470-4900; www.icps2002.org.

## AUGUST 2002

**18-23** Intl. Conf. on Electrophoretic Deposition: Fundamentals and Applications, Banff, Canada. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**20-7** ▼ 23rd Intl. Conf. on Low-Temperature Physics, Hiroshima, Japan. Japan Convention Services, Inc., LT23, Nippon Press Ctr., Bldg., 2-2-1, Uchisaiwaicho, Chiyodaku, Tokyo 100-0011, Japan; 81-3-3508-1214; e-mail lt23@convention.co.jp; www.issp.u-tokyo.ac.jp/lt23/.

**25-29** Conf. on Fluid Particle Interactions, Barga, Italy. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**28-31** 2nd Intl. Mould & Die Making and Manufacturing Technology Exhibition for Asia, Hong Kong. Business and Industrial Trade Fairs Ltd., Unit 1223, HITEC, 1 Trademart Dr., Kowloon Bay, Hong Kong; 852-2865-2633; fax 852-2866-1770; e-mail enquiry@bitf.com.hk.

## SEPTEMBER 2002

**4-6** 35th Intl. Symposium on Microelectronics, Denver, CO. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**8-12** 6th Intl. Meeting on Magnetic Resonance in Porous Media, Ulm, Germany. www.uni-ulm.de/nmr/mrpm6/early\_notification.htm.

**16-20** Intl. Conf. on Shot Peening, Garmisch-Partenkirchen, Germany. P. Schepp, Deutsche Gesellschaft für Materialkunde e.V., Hamburger Allee 26, D-60486 Frankfurt, Germany; 49-69-7917-750; fax 49-69-7917-733; e-mail shot-peening@dgm.de; www.dgm.de/shot-peening.

**24-27** 3rd World Congress on Emulsions, Lyon, France. CME, 50 Place Marcel Pagnol, 92100 Boulogne-Billancourt, France; 33-147-617-689; fax 33-147-617-465; e-mail alain.lecoroller@wanadoo.fr; www.cme-emulsion.com.

## OCTOBER 2002

**1-4** ▼ 54th Pacific Coast Regional and ACerS Basic Science Div. Meeting, Seattle, WA. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

**6-10** TMS Fall Meeting, Columbus, OH. TMS Programming Dept., 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail ckobert@tms.org; www.tms.org.

**12-15** ▼ ACerS Glass and Optical Materials Div. Meeting, Pittsburgh, PA. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

**20-25** 202nd Meeting of the Electrochemical Society, Salt Lake City, UT. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

**29-3** ▼ ABET Annual Meeting, Pittsburgh, PA. 2002 ABET Annual Meeting, 11 Market Place, Ste. 1050, Baltimore, MD 21202-4012; www.abet.org.

## NOVEMBER 2002

**11-15** 44th Annual Meeting of the APS Division of Plasma Physics, Orlando, FL. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

## DECEMBER 2002

**2-6** MRS Fall Meeting, Boston, MA. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**